
IBIS/HSPICE Model Quality Report

Design ID: **Y66A**

Description: **256Mb - x8, x16 SDRAM**

Marketing device name(s): **MT48LC32M8A2TG, MT48LC16M16A2TG, MT48LC32M8A2BB, MT48LC16M16A2BG, MT48LC32M8A2Y66A, MT48LC16M16A2Y66A**

Valid speed grades: **SDRAM-100, 133, 143, 167 MHz**

Zip filename: **y66a_ibis.zip**

IBIS filename: **y66a.ibs, y66a_at.ibs, y66a_it.ibs** File rev: **2.0**

HSpice filename: **y66a_hspice.zip** File rev: **2.0**

EBD filename (if applicable): **N/A** File rev: **N/A**

Die rev: **G**

Date: **July 19, 2011**

Datasheet Link (from micron.com): go to <http://www.micron.com/my.html> and search columns for y66a

E-mail modelsupport@micron.com for questions regarding Quality Report.

Device Parameters

VDDQ – Slow: **3.0** Typical: **3.3** Fast: **3.6**

VDD – Slow: **3.0** Typical: **3.3** Fast: **3.6**

Junction Temperature (Commercial) - Slow: **85C** Typical: **50C** Fast: **0C**

Junction Temperature (Industrial) - Slow: **95C** Typical: **50C** Fast: **-40C**

Junction Temperature (Automotive) - Slow: **110C** Typical: **50C** Fast: **-40C**

VDDQ/VSSQ Decoupling Capacitance: **3.571nF**

Included in HSPICE DQ/DQS models? **YES** Amount per DQ/DQS model: **111.59pF**

VDDQ/VSSQ Decoupling Capacitance Series Resistance: **11.77 Ohms**

IBIS Quality Summary

1. ☒ Include the IBIS Quality Specification 2.0 Overall IBIS Quality level. For details on IBIS Quality, reference the quality specification and quality checklist on IBIS quality webpage http://www.eda.org/pub/ibis/quality_wip/.

Overall IBIS Quality Level: **3MS**

Exceptions: **0**

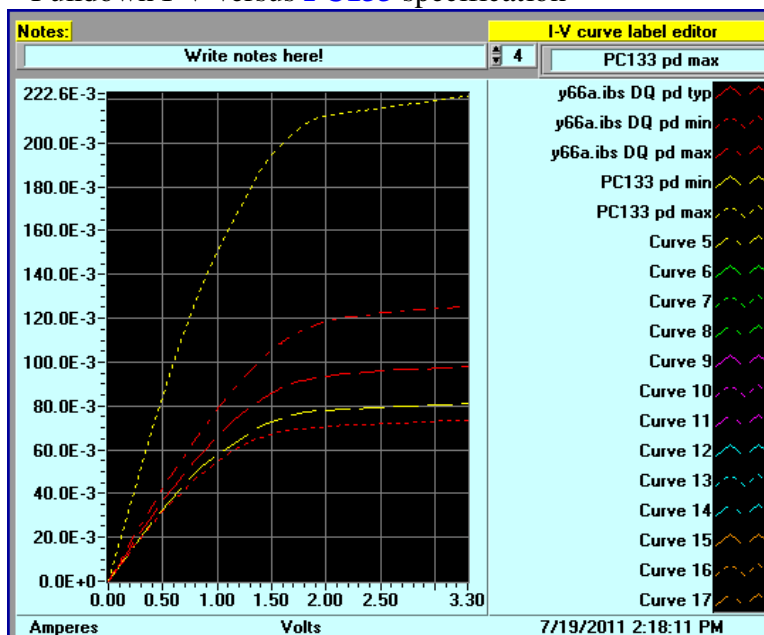
2. ☒ Include the filename of the IBIS Quality Checklist that accompanies this report.

Filename: **y66a_ibis_quality_2.0_checklist.xls**

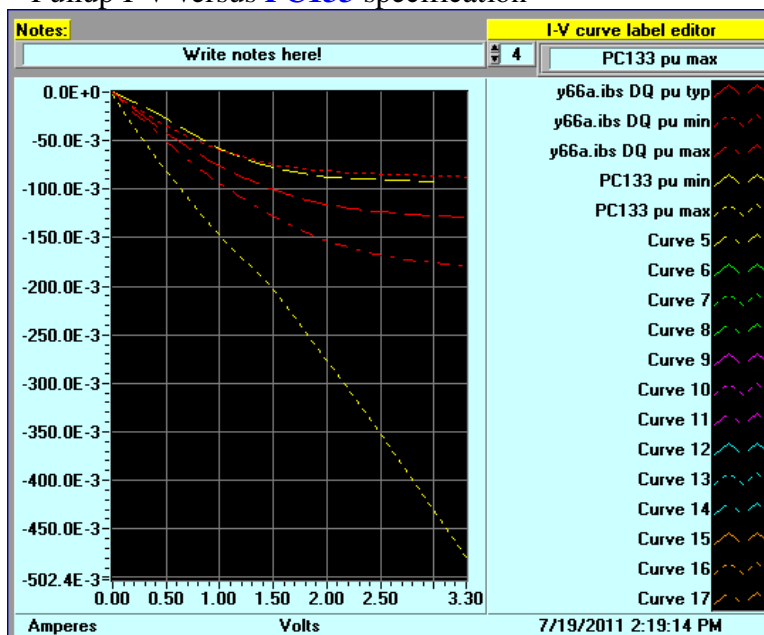
IBIS MODEL Correlation

Datasheet Correlation

1. ☒ For Output or I/O model compare datasheet IOH/IOL data with IBIS pullup/pulldown data.
 - a. Model name: **DQ**
 - i. Pulldown I-V versus **PC133** specification



- ii. Pullup I-V versus **PC133** specification



2. ☒ Compare C_comp with datasheet Input C. Provide C_comp comparison table for all models and for all package combinations (i.e. x4, x8 and x16).

Component name: **MT48LC32M8A2BB (60-ball FBGA)**

		IBIS		Datasheet	
		min	max	min	max
DQ	C_comp	3.72	4.02	NA	NA
	C_package	0.72	1.26	NA	NA
	C_total	4.44	5.28	3.00	6.00
INPUT	C_comp	2.15	2.35	NA	NA
	C_package	0.67	1.08	NA	NA
	C_total	2.82	3.43	1.50	3.80
CLK	C_comp	2.23	2.43	NA	NA
	C_package	0.83	0.83	NA	NA
	C_total	3.06	3.26	1.50	3.50
DM	C_comp	2.58	2.78	NA	NA
	C_package	0.72	0.72	NA	NA
	C_total	3.29	3.49	1.50	3.80

Component name: **MT48LC16M16A2BG (54-ball VFBGA)**

		IBIS		Datasheet	
		min	max	min	max
DQ	C_comp	3.72	4.02	NA	NA
	C_package	0.63	1.09	NA	NA
	C_total	4.35	5.12	3.00	6.00
INPUT	C_comp	2.15	2.35	NA	NA
	C_package	0.65	1.01	NA	NA
	C_total	2.80	3.35	1.50	3.80
CLK	C_comp	2.23	2.43	NA	NA
	C_package	0.74	0.74	NA	NA
	C_total	2.97	3.17	1.50	3.50
DM	C_comp	2.58	2.78	NA	NA
	C_package	0.68	0.91	NA	NA
	C_total	3.25	3.69	1.50	3.80

Component name: **MT48LC32M8A2TG (54-pin TSOP)**

		IBIS		Datasheet	
		min	max	min	max
DQ	C_comp	3.72	4.02	NA	NA
	C_package	0.41	0.78	NA	NA
	C_total	4.13	4.80	4.00	6.00
INPUT	C_comp	2.15	2.35	NA	NA
	C_package	0.63	0.94	NA	NA
	C_total	2.78	3.29	2.50	3.80
CLK	C_comp	2.23	2.43	NA	NA
	C_package	0.68	0.68	NA	NA
	C_total	2.91	3.11	2.50	3.50
DM	C_comp	2.58	2.78	NA	NA
	C_package	0.63	0.63	NA	NA
	C_total	3.21	3.41	2.50	3.80

Component name: **MT48LC16M16A2TG (54-pin TSOP)**

		IBIS		Datasheet	
		min	max	min	max
DQ	C_comp	3.72	4.02	NA	NA
	C_package	0.41	0.78	NA	NA
	C_total	4.13	4.80	4.00	6.00
INPUT	C_comp	2.15	2.35	NA	NA
	C_package	0.63	0.94	NA	NA
	C_total	2.78	3.29	2.50	3.80
CLK	C_comp	2.23	2.43	NA	NA
	C_package	0.68	0.68	NA	NA
	C_total	2.91	3.11	2.50	3.50
DM	C_comp	2.58	2.78	NA	NA
	C_package	0.58	0.63	NA	NA
	C_total	3.15	3.41	2.50	3.80

3. ☐ If slew rate specifications (rise/fall slew) are available from the datasheet, complete HSpice simulations to generate slew rate data and provide a comparison table.

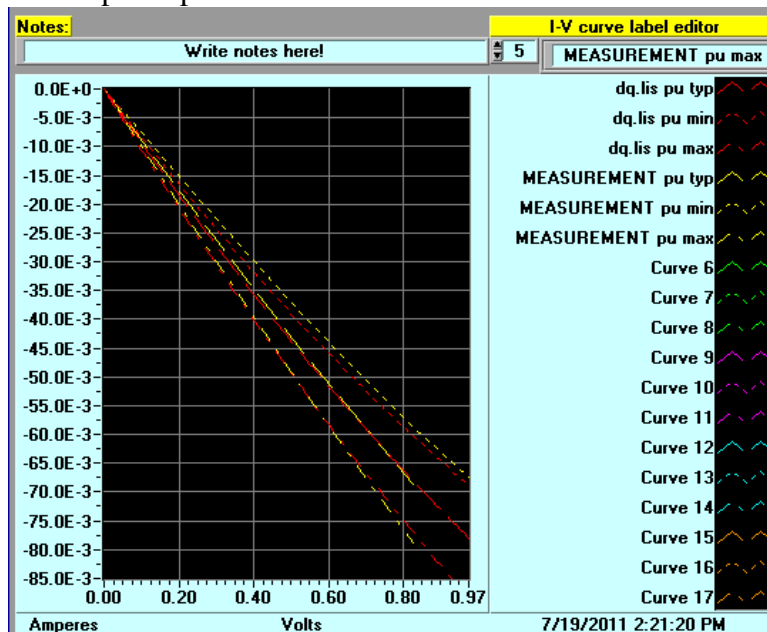
Not Available

4. ☐ Compare ODT data with datasheet.

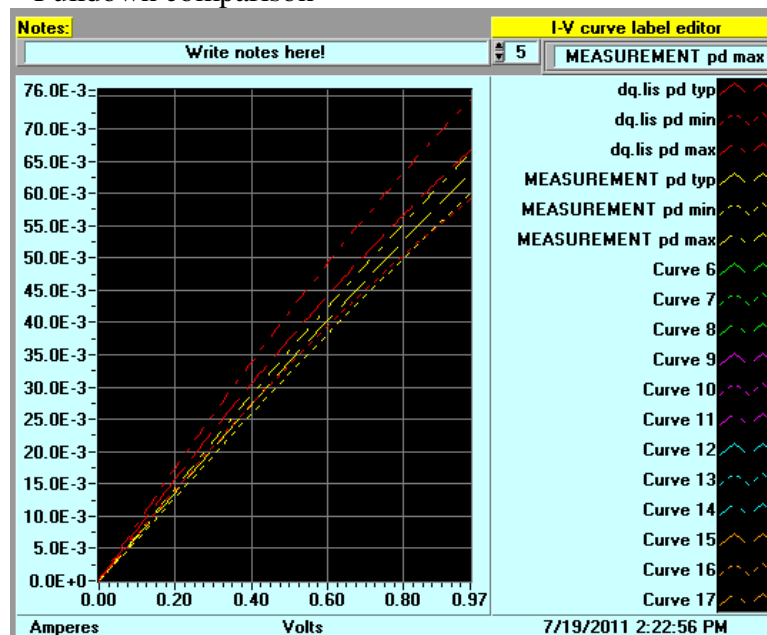
Not Applicable

Measurement Correlation

1. ☒ For Output or I/O models compare measured IOH/IOL data with IBIS pullup/pulldown data. If the measurement conditions are different than the IBIS conditions, run HSpice simulations using the same measurement conditions such as VCC, temperature, and process. Include measurement conditions in the pullup/pulldown images.
 - a. Model name: **DQ (measurement range 0-0.975V)**
 - i. Pullup comparison



- ii. Pulldown comparison



2. ☒ Compare C_comp with measured C_comp. Provide C_comp comparison table for all models and for all package combinations (i.e x4, x8 and x16).

Component name: **MT48LC32M8A2BB (60-ball FBGA)**

		IBIS			Measured		
		min	typ	max	min	typ	max
DQ	C_comp	3.72	3.87	4.02	NA	NA	NA
	C_package	0.72	1.06	1.26	NA	NA	NA
	C_total	4.44	4.93	5.28	4.55	4.93	5.40
INPUT	C_comp	2.15	2.25	2.35	NA	NA	NA
	C_package	0.67	0.93	1.08	NA	NA	NA
	C_total	2.82	3.17	3.43	2.75	3.17	3.43
CLK	C_comp	2.23	2.33	2.43	NA	NA	NA
	C_package	0.83	0.83	0.83	NA	NA	NA
	C_total	3.06	3.16	3.26	3.09	3.16	3.20
DM	C_comp	2.58	2.68	2.78	NA	NA	NA
	C_package	0.72	0.72	0.72	NA	NA	NA
	C_total	3.29	3.39	3.49	3.34	3.39	3.43

Component name: **MT48LC16M16A2BG (54-ball VFBGA)**

		IBIS			Measured		
		min	typ	max	min	typ	max
DQ	C_comp	3.72	3.87	4.02	NA	NA	NA
	C_package	0.63	0.87	1.09	NA	NA	NA
	C_total	4.35	4.74	5.12	4.30	4.76	5.14
INPUT	C_comp	2.15	2.25	2.35	NA	NA	NA
	C_package	0.65	0.80	1.01	NA	NA	NA
	C_total	2.80	3.04	3.35	2.82	3.02	3.31
CLK	C_comp	2.23	2.33	2.43	NA	NA	NA
	C_package	0.74	0.74	0.74	NA	NA	NA
	C_total	2.97	3.07	3.17	2.93	2.98	3.01
DM	C_comp	2.58	2.68	2.78	NA	NA	NA
	C_package	0.68	0.80	0.91	NA	NA	NA
	C_total	3.25	3.47	3.69	3.29	3.47	3.62

Component name: **MT48LC16M16A2TG (54-pin TSOP)**

		IBIS			Measured		
		min	typ	max	min	typ	max
DQ	C_comp	3.72	3.87	4.02	NA	NA	NA
	C_package	0.41	0.59	0.78	NA	NA	NA
	C_total	4.13	4.46	4.80	4.15	4.47	4.99
INPUT	C_comp	2.15	2.25	2.35	NA	NA	NA
	C_package	0.63	0.79	0.94	NA	NA	NA
	C_total	2.78	3.03	3.29	2.60	3.11	3.43
CLK	C_comp	2.23	2.33	2.43	NA	NA	NA
	C_package	0.68	0.68	0.68	NA	NA	NA
	C_total	2.91	3.01	3.11	2.78	2.90	3.01
DM	C_comp	2.58	2.68	2.78	NA	NA	NA
	C_package	0.58	0.61	0.63	NA	NA	NA
	C_total	3.15	3.28	3.41	3.04	3.20	3.33

3. ☐ If measured clamp current data is available provide an IBIS and measurement comparison for all models.

Not Available

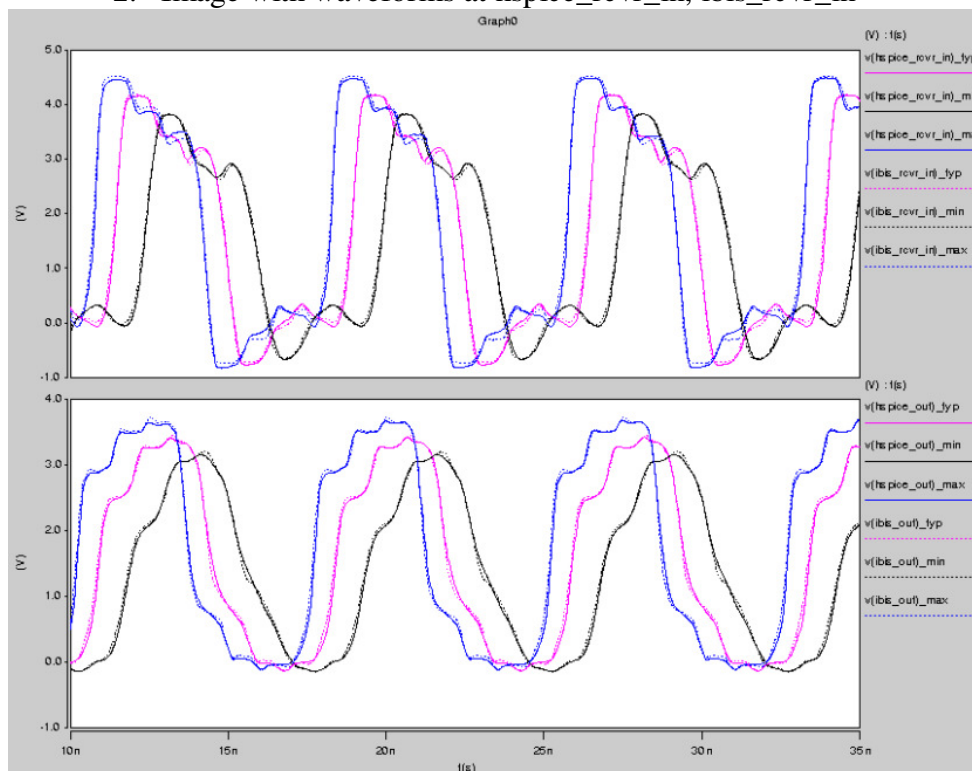
4. ☐ If slew rate data (rise/fall slew) is available from measurements, complete HSpice simulations to generate slew rate data and provide a comparison table.

Not Available

		IBIS			Measurement	
Model	Slew Rate (V/ns)	min	typ	max	min	max
DQ_FULL	Rising					
	Falling					
DQ_HALF	Rising					
	Falling					

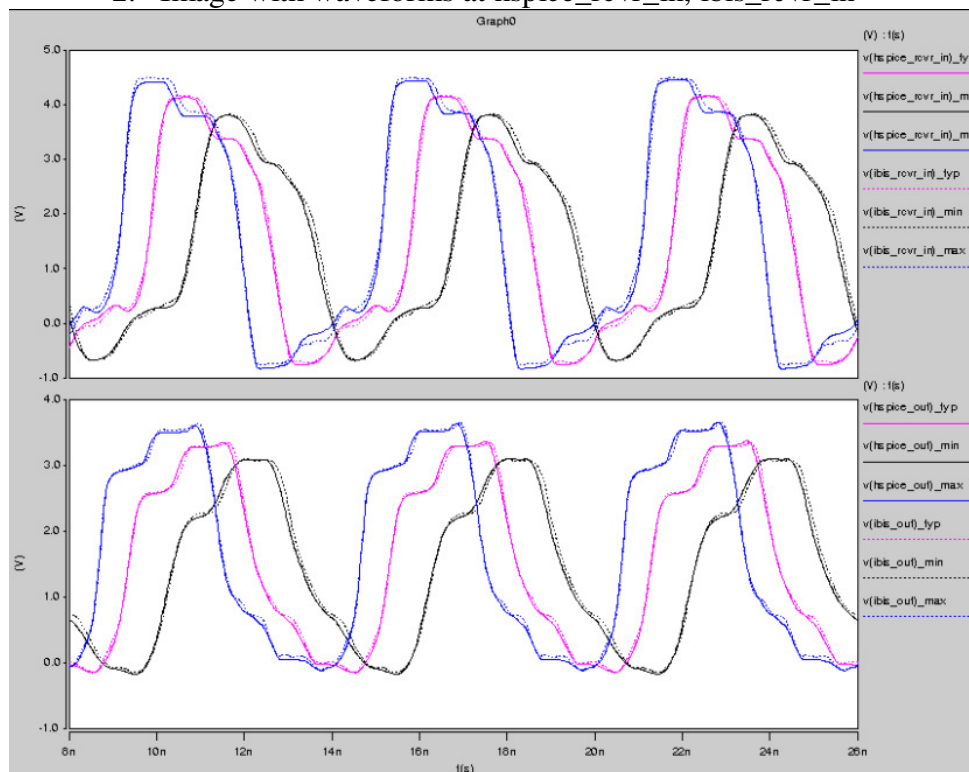
IBIS vs HSPICE Correlation

1. ☒ For all Output or I/O models, run HSpice transient simulations using encrypted netlists and the IBIS model (b-element).
 - a. ☒ Use the setup and node naming conventions shown below for the IBIS and HSpice deck file (.sp file). Update the setup diagram if it is different. Indicate the version of HSPICE simulator used for simulations: **2008.09**
 - b. ☒ Run simulations for all corners cases and at maximum allowable speed grade
 - i. DQ driving DQ at 133 MHz
 1. Image with waveforms at hspice_out, ibis_out
 2. Image with waveforms at hspice_rcvr_in, ibis_rcvr_in



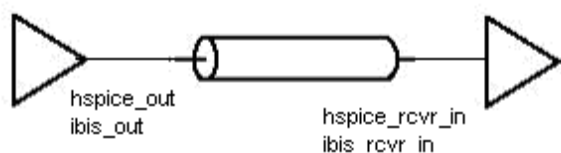
ii. DQ driving DQ at 167 MHz

1. Image with waveforms at hspice_out, ibis_out
2. Image with waveforms at hspice_rcvr_in, ibis_rcvr_in



Setup

T-line: Z0 50 ohms,
Td=0.5ns



Comments:

Document Revision History

Rev 1.0 - Date 12/13/2010

- a. IBIS revision 1.0
- b. HSpice revision 1.0

Rev 2.0 - Date 07/19/2011

- a. IBIS revision 2.0
- b. HSpice revision 2.0